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(12) **United States Design Patent**
Podubni

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(54) **MODULAR CIRCUIT BOARD**

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(73) Assignee: **TinyPCB, Inc.**

(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**

USPC **D13/182**

(58) **Field of Classification Search**

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361/761, 807; 439/55, 65, 68, 76.1, 92,
439/93, 95

CPC H05K 3/00; H05K 3/30; H05K 3/301;
H05K 3/303; H05K 3/34; H05K 3/3405;
H05K 3/341; H05K 3/36; H05K 3/361;
H05K 3/363; H05K 3/40; H05K 1/18;
H05K 1/02; H05K 1/181; H05K 1/182;
H05K 1/183; H05K 1/184; H05K 1/189;
H05K 1/00

See application file for complete search history.

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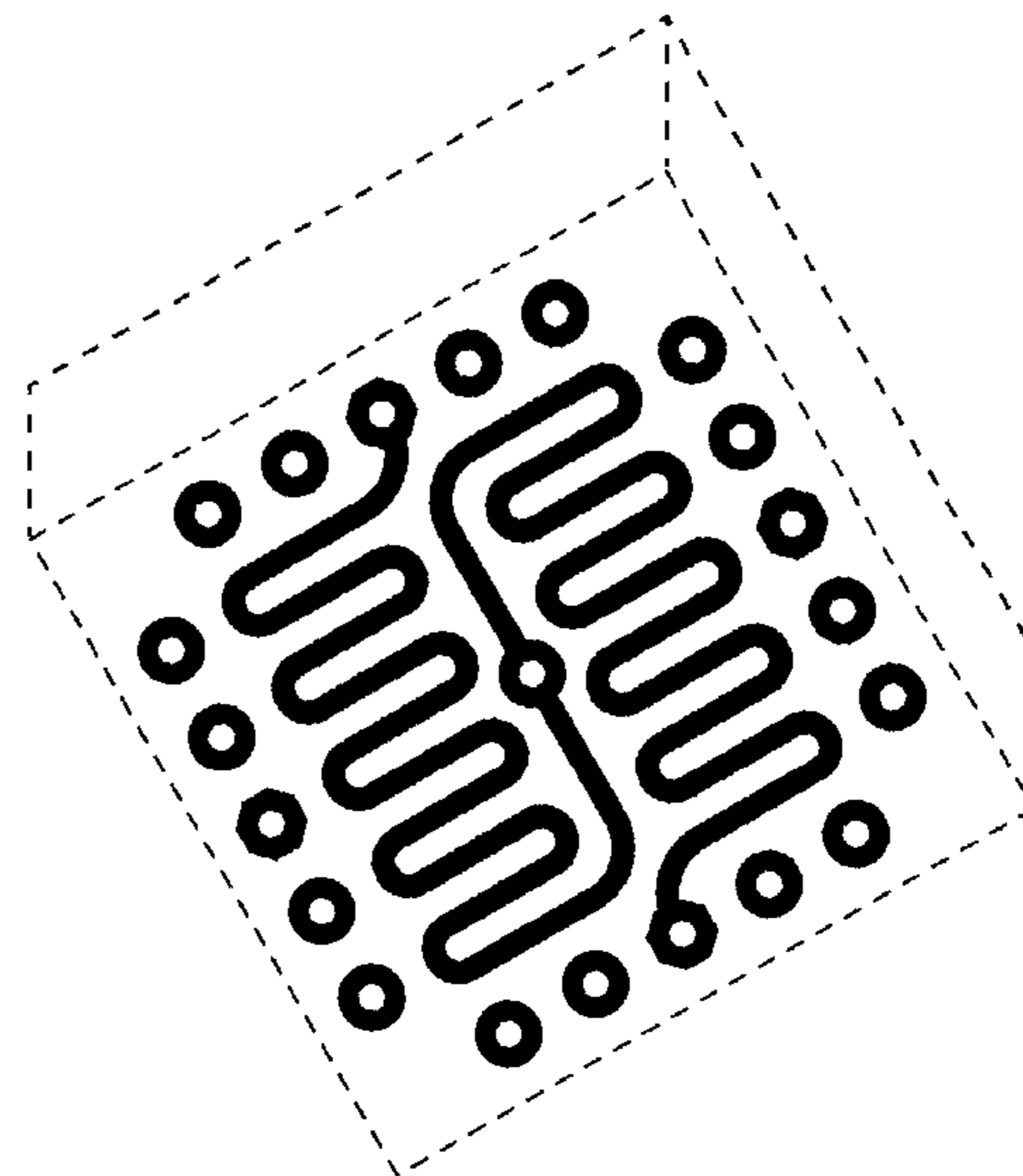
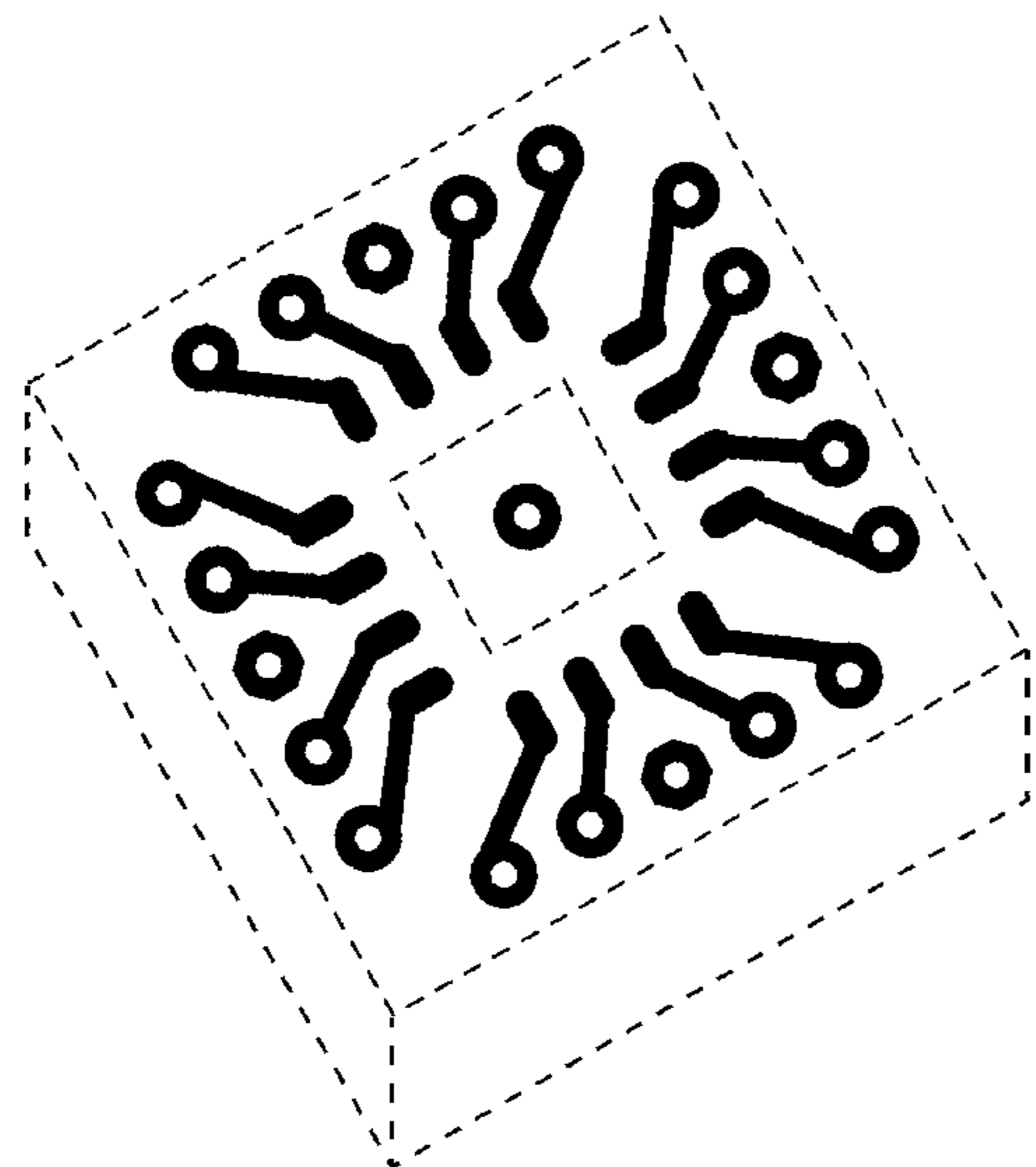
(57) **CLAIM**

The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;
FIG. 2 is a bottom perspective view thereof;
FIG. 3 is a top view thereof;
FIG. 4 is a bottom view thereof; and,
FIG. 5 is a side view thereof, all other side views being a mirror image thereof.
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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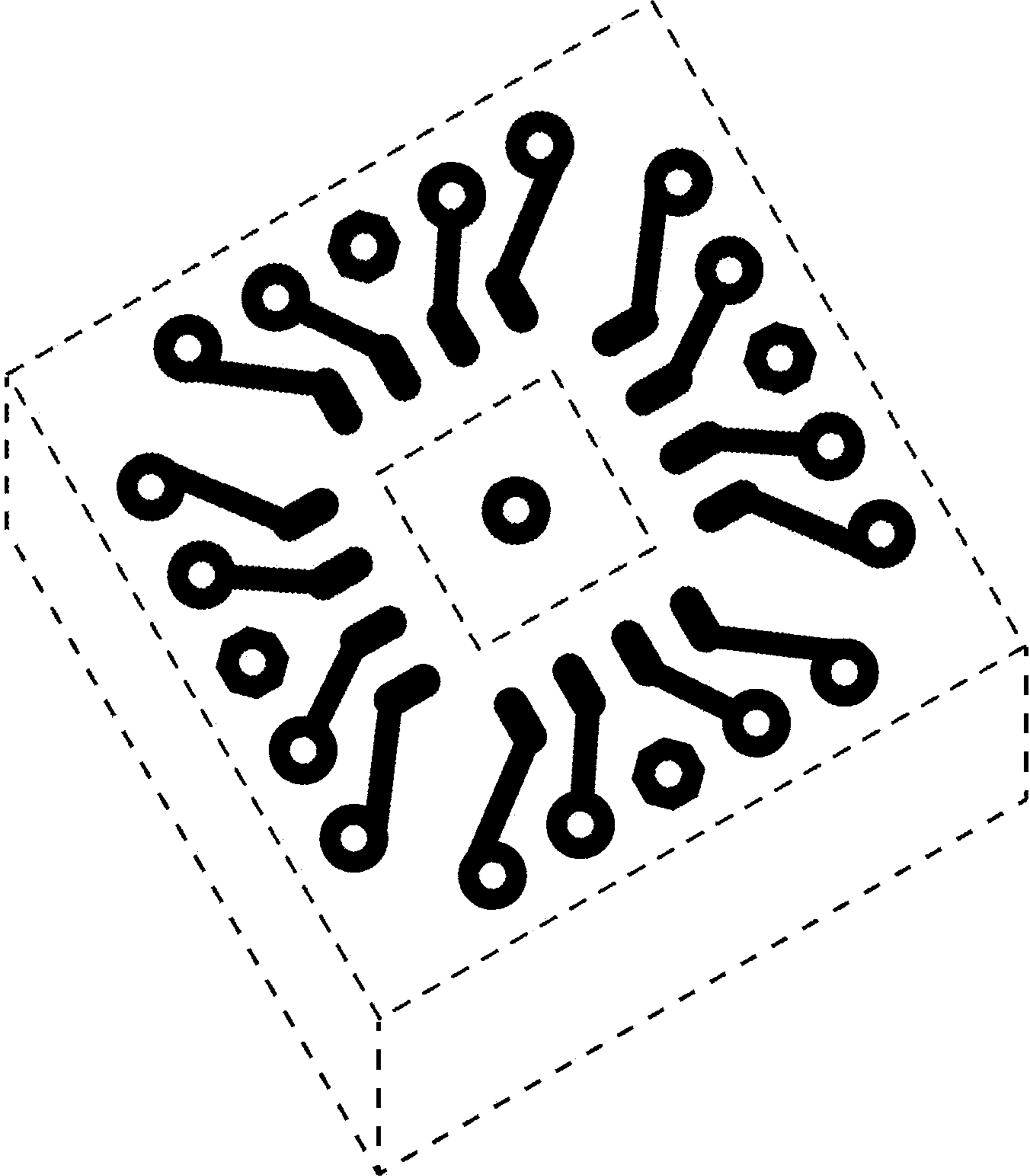


FIG. 1

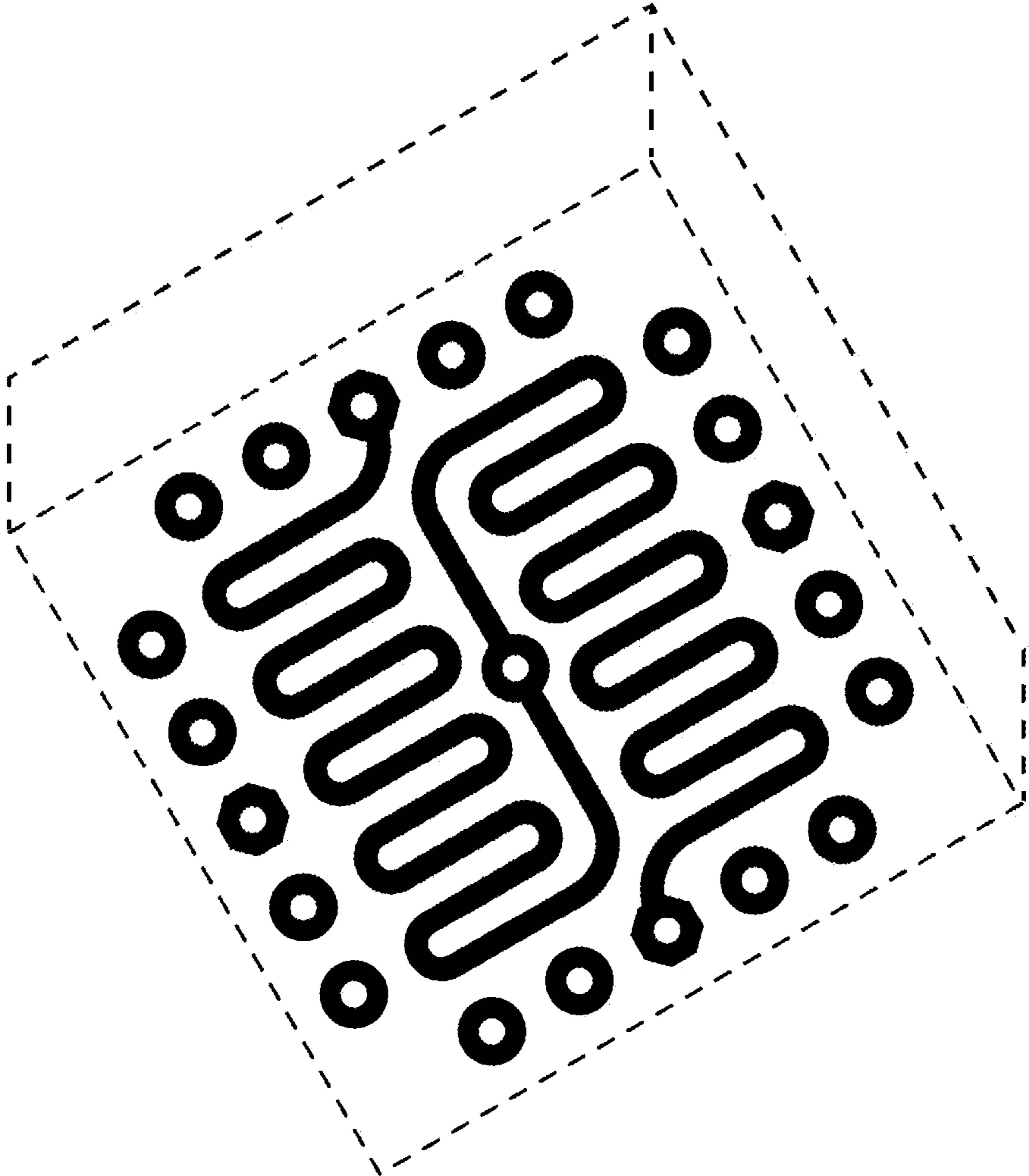


FIG. 2

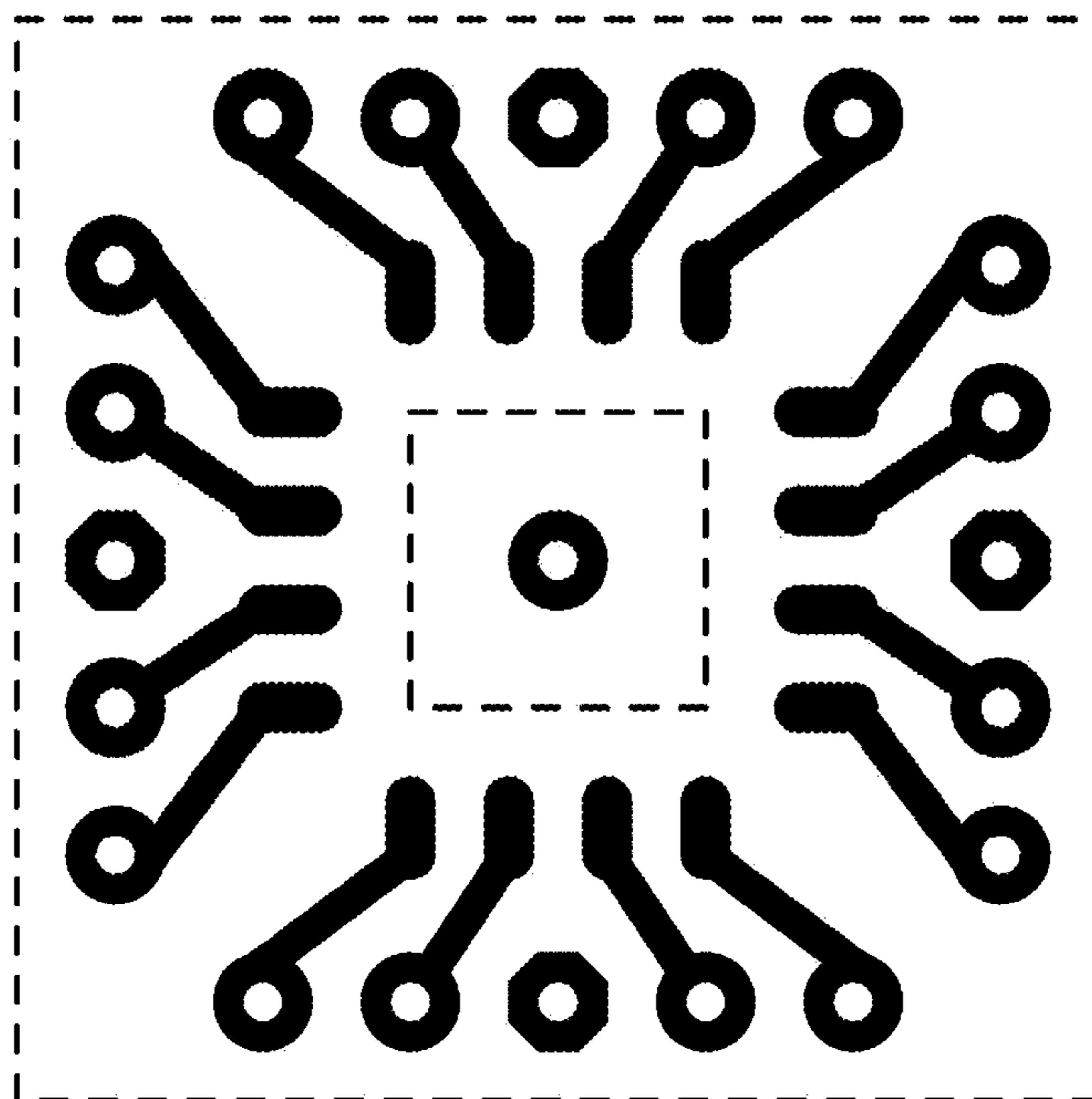


FIG. 3

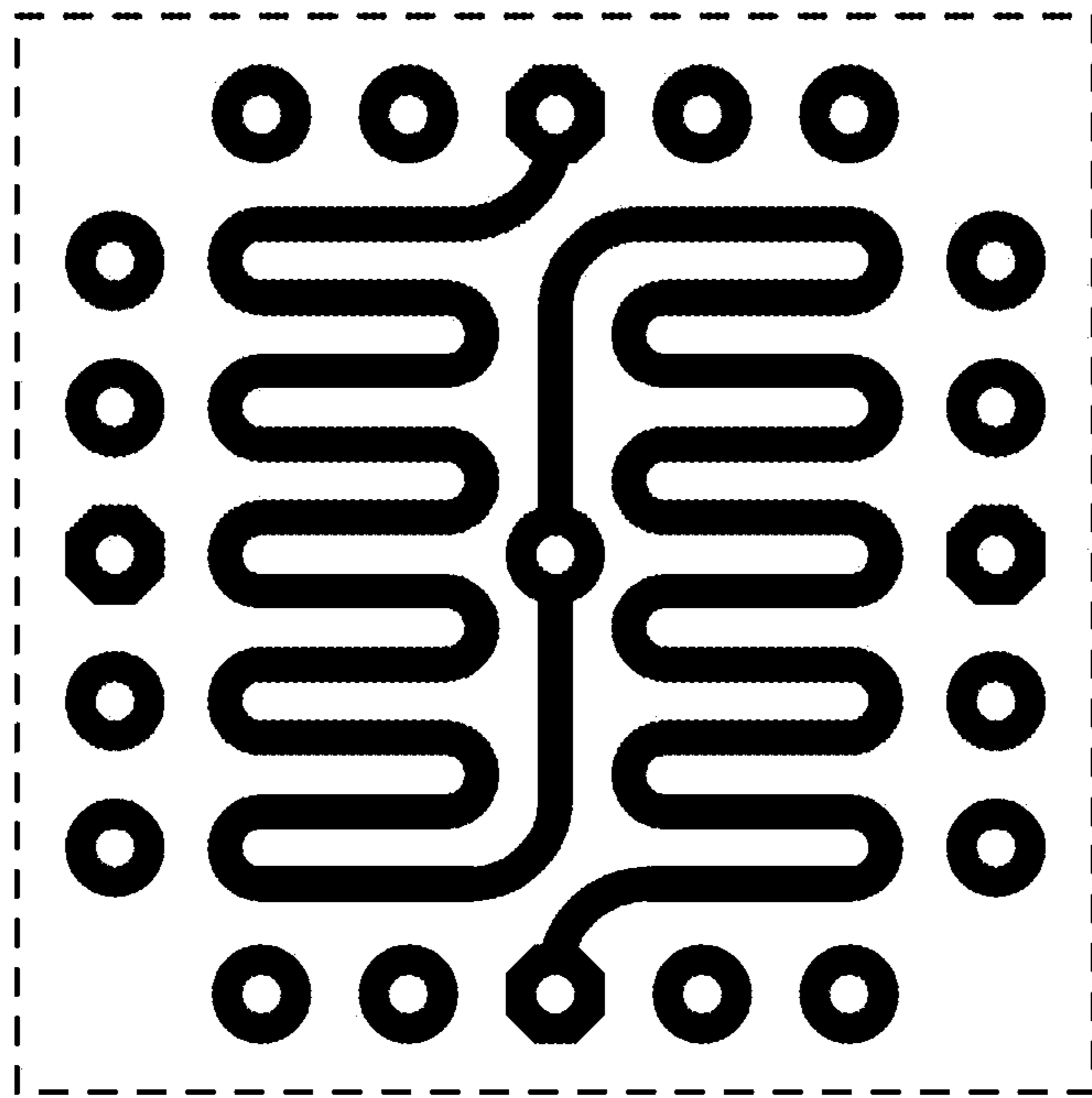


FIG. 4

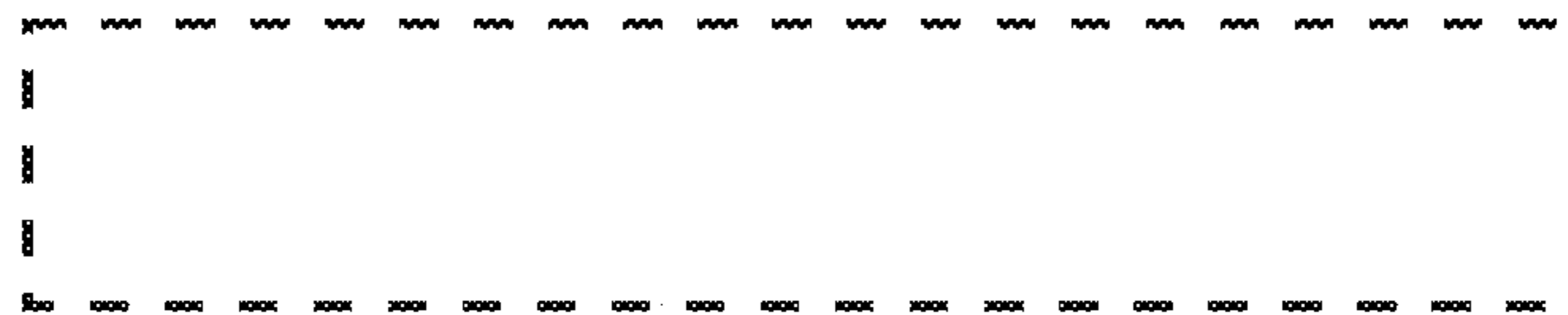


FIG. 5